

General Description

The WSP4884 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate chargens for most of the synchronous buck converter applications .

The WSP4884 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

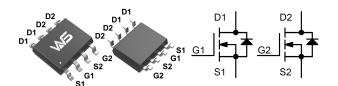
Product Summery

BVDSS	RDSON	ID
30V	18.5m Ω	8.8A

Application

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	8.8	Α
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	7.0	Α
I _{DM}	Pulsed Drain Current ²	40	Α
EAS	Single Pulse Avalanche Energy ³	20	mJ
I _{AS}	Avalanche Current	9	А
P _D @T _A =25℃	Total Power Dissipation⁴	2.0	W
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$ C
T_J	Operating Junction Temperature Range -55 to 150		$^{\circ}$ C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		90	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		50	°C/W



Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.034		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =8.5A		18.5	23	m()
R _{DS(ON)}		V _{GS} =4.5V , I _D =5A		25	27	mΩ
$V_{GS(th)}$	Gate Threshold Voltage		1.5	1.8	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} , I _D -230UA		-5.8		mV/℃
	Drain Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =55 $^{\circ}$ C			5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =8A		6		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7	2.5	Ω
Qg	Total Gate Charge (4.5V)	V _{DS} =15V , V _{GS} =4.5V , I _D =8.8A		6	8.4	
Q_gs	Gate-Source Charge			1.5		nC
Q_{gd}	Gate-Drain Charge			2.5		
$T_{d(on)}$	Turn-On Delay Time			6	8.8	
T _r	Rise Time	V_{DD} =15V , V_{GEN} =10V , R_{G} =6 Ω I_{D} =1A, R_{L} =15 Ω		8.2	14	
T _{d(off)}	Turn-Off Delay Time			16	24	ns
T _f	Fall Time			4	8	
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		580	701	
C _{oss}	Output Capacitance			95	112	pF
C _{rss}	Reverse Transfer Capacitance			57	91	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =9A	18			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			2	Α
I _{SM}	Pulsed Source Current ^{2,6}	V _G -V _D -0V , Force Current			40	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_S =1A , T_J =25 $^{\circ}{\mathbb{C}}$			1.1	V
t _{rr}	Reverse Recovery Time			12		nS
Q _{rr}	Reverse Recovery Charge	IF=8A , dI/dt=100A/ μ s , T $_{J}$ =25 $^{\circ}$ C		3.5		nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.5mH, I_{AS} =9A
- 4.The power dissipation is limited by 150 ℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

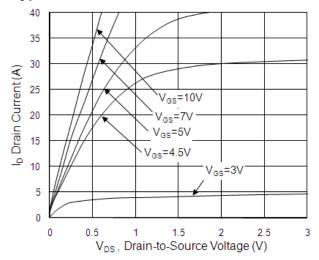


Fig.1 Typical Output Characteristics

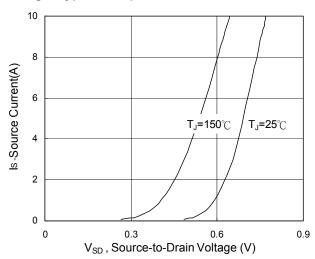
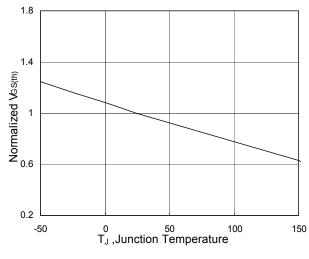


Fig.3 Forward Characteristics Of Reverse



(°C)ÆFig.5 Normalized $V_{GS(th)}$ vs. T_J

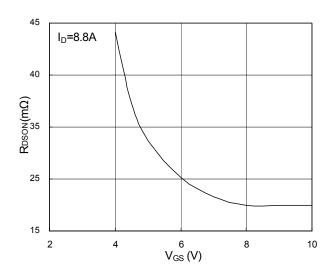


Fig.2 On-Resistance vs. G-S Voltage

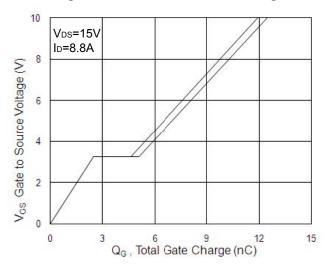


Fig.4 Gate-Charge Characteristics

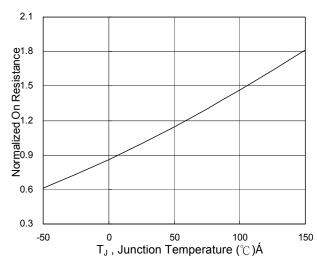
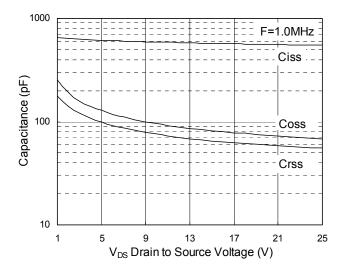


Fig.6 Normalized R_{DSON} vs. T_J





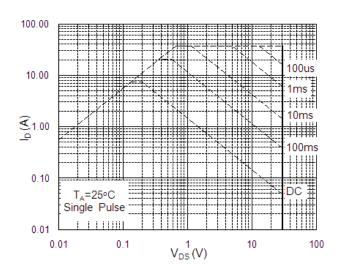


Fig.7 Capacitance

Fig.8 Safe Operating Area

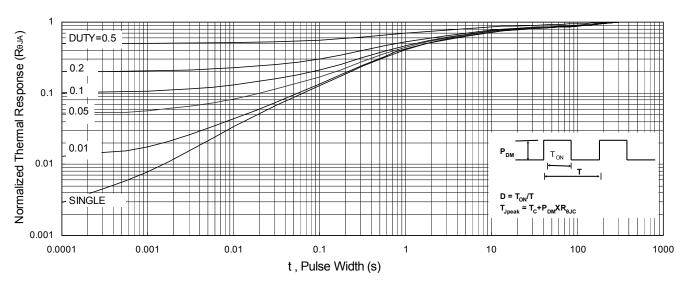


Fig.9 Normalized Maximum Transient Thermal Impedance

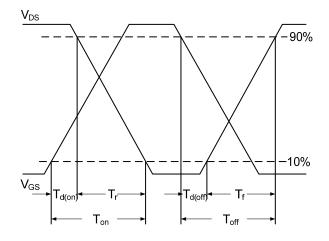


Fig.10 Switching Time Waveform

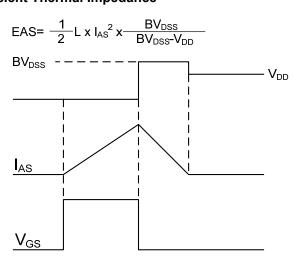


Fig.11 Unclamped Inductive Switching Waveform



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